L Number	Hits	Search Text	DB	Time stamp
3	36	438/705 and sacrificial	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 15:35
4	26441	etch$ adj2 (rate? time selectivity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 14:01
5	867	(etch$ adj2 (rate? time selectivity)) same mask?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 13:54
6	16	((etch$ adj2 (rate? time selectivity)) same mask?) same sacrificial	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 13:54
7	3808	etch$ adj rate? with (different high$2 low$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 14:36
8	135	(etch$ adj rate? with (different high$2 low$2)) and stack?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 14:08
9	12	((etch$ adj rate? with (different high$2 low$2)) and stack?) and semiconductor?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 14:03
10	161	(etch$ adj rate? with (different high$2 low$2)) same simultaneous$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 14:09
11	45	((etch$ adj rate? with (different high$2 low$2)) same simultaneous$2) same layer?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 14:20
12	2803	(438/745,750,751-752,705,707,710,714,604-606).CCLS.	USPAT	2004/03/19 14:21
13	28	etch$ adj rate? with different with simultaneous$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 15:39
14	927	(438/735-739).CCLS.	USPAT	2004/03/19 15:37
15	307	((438/735-739).CCLS.) and protect$4 with etch$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 15:41
16	12	((438/735-739).CCLS.) and protect$4 with etch$3 same etch$3 near5 rate?	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/19 15:42